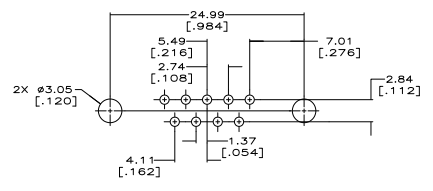
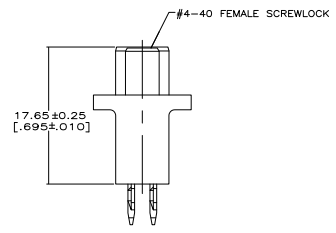
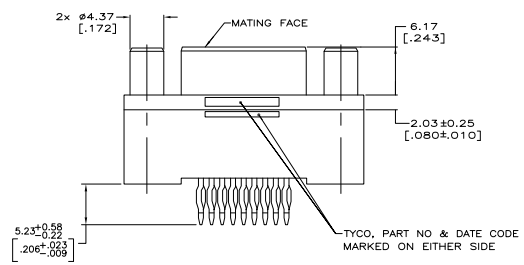


RECOMMENDATIONS FOR 2.36[.093] MIN THICK PC BOARD:
 A. HOLE DIAMETER AFTER DRILLING=1.14±0.03[0.045±.001]
 B. HOLE DIAMETER AFTER TIN PLATING= 0.94-1.09 [0.37-.043]
 C. HOLE DIAMETER AFTER REFLOW= 0.91-1.09 [0.36-.043]
 D. PC BOARD PLATING TO BE 7.62μm[0.000300] MIN TIN OVER 0.05±0.03[.002±.001] COPPER.

MATERIAL:
 HOUSING: GLASS-FILLED NYLON OR POLYESTER, UL94V-0 RATED, COLOR:BLACK.
 CONTACTS: COPPER ALLOY.
 SCREWLOCKS: BRASS.

SCREWLOCKS: 0.00127[.000050] MIN NICKEL OVER COPPER FLASH.

CONTACTS:
 0.76 MICROMETERS [0.000030]MIN GOLD IN MATING AREA.
 2.54 MICROMETERS [0.00100]MIN TIN ON COMPLIANT PIN.
 ALL OVER 1.27 MICROMETERS [0.000050]MIN NICKEL.
 OR
 GOLD FLASH OVER PALLADIUM NICKEL.
 0.76 MICROMETERS [0.000030]MIN TOTAL IN MATING AREA.
 2.54 MICROMETERS [0.00100]MIN TIN ON COMPLIANT PIN.
 ALL OVER 1.27 MICROMETERS [0.000050]MIN NICKEL.



RECOMMENDED PC BOARD MOUNTING DIMENSIONS △
 CONNECTOR SIDE OF BOARD

5745455-2
 PART NUMBER

THIS DRAWING IS A CONTROLLED DOCUMENT.		REV: 00	DATE: 10/10/04	BY: HMR	APP: JL
DRAWING NO: 5745455-2		REV: 00	DATE: 10/10/04	BY: HMR	APP: JL
DESCRIPTION: RECEPTACLE ASSEMBLY ACTION-PIN, 9 POSITION, HD-20, AMPPLITE		REV: 00	DATE: 10/10/04	BY: HMR	APP: JL
MATERIAL: NYLON		REV: 00	DATE: 10/10/04	BY: HMR	APP: JL
FINISH: POLISH		REV: 00	DATE: 10/10/04	BY: HMR	APP: JL
PROCESS: 108-40014		REV: 00	DATE: 10/10/04	BY: HMR	APP: JL
CUST. DRAWING		REV: 00	DATE: 10/10/04	BY: HMR	APP: JL